

General Description

The Si2328DS-T1-GE3 use advanced SGT MOSFET technology to provide low RDS(ON), low gate charge, fast switching and excellent avalanche characteristics. This device is specially designed to get better ruggedness and suitable to use in

General Features

V_{DS} =100V I_D =5 A

 $R_{DS(ON)}$ < 140m Ω @ V_{GS}=10V

Applications

Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications

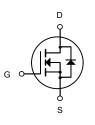
Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
Si2328DS-T1-GE3	SOT-23-3L	HXY MOSFET	3000

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter Rating			
Vds	Drain-Source Voltage 100			
Vgs	Gate-Source Voltage ±20			
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V 5			
I _D @T _C =70 °C	Continuous Drain Current, V _{GS} @ 10V 2.2			
Ідм	Pulsed Drain Current ² 11		А	
PD@Tc=25°C	Total Power Dissipation ⁴ 1		W	
Тѕтс	Storage Temperature Range -55 to 150 °C		°C	
TJ	Operating Junction Temperature Range -55 to 150		°C	
R _θ JC	Thermal Resistance from Junction-to-Ambient ³	ce from Junction-to-Ambient ³ 80 °C/W		
Reja	Thermal Resistance Junction-Ambient ¹ 125 °C,		°C/W	





N-Channel MOSFET

Si2328DS-T1-GE3

N-SGT Enhancement Mode MOSFET



Electrical Characteristics Tc=25°C unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Chara	Off Characteristic					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250µA	100	110	-	V
IDSS	Zero Gate Voltage Drain Current	V _{DS} = 100V, V _{GS} = 0V	-	-	1	μA
Igss	Gate to Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Chara	cteristics ^{note3}		•		•	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.0	1.95	3.0	V
R _{DS(on)}	Static Drain-Source On-Resistance note2	V _{GS} = 10V, I _D = 3A	-	95	140	mΩ
Dynamic (Characteristics note4					
Ciss	Input Capacitance	V _{DS} = 50V, V _{GS} = 0V,	-	196	-	pF
Coss	Output Capacitance		-	25.9	-	pF
C _{rss}	Reverse Transfer Capacitance	f = 1.0MHz	-	21.4	-	pF
Qg	Total Gate Charge	$V_{DS} = 50V, I_D = 3A,$	-	4.3	-	nC
Qgs	Gate-Source Charge		-	3.5	-	nC
Q _{gd}	Gate-Drain("Miller") Charge	V _{GS} = 10V	-	3.1	-	nC
Switching	Characteristics note4					
t _{d(on)}	Turn-On Delay Time		-	14.7	-	ns
tr	Turn-On Rise Time	$V_{DD} = 50V, I_{DS} = 3A$		3.5	-	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 2\Omega, V_{GEN} = 10V$	-	20.9	-	ns
t _f	Turn-Off Fall Time		-	2.7	-	ns
Drain-Sou	rce Diode Characteristics and Maximum Rati	ngs				
Is	Maximum Continuous Drain to Source Diode Forward Current note2		-	-	4.5	А
Ism	Maximum Pulsed Drain to Source Diode Forward Current		-	-	12	А
V _{SD}	Drain to Source Diode Forward Voltage ^{note3} V _{GS} = 0V, I _S =3A		-	-	1.3	V
trr	Body Diode Reverse Recovery Time		-	32.1	-	ns
Qrr	Body Diode Reverse Recovery Time Charge	$V_{GS} = 0V, I_F = 3A,$	-	39.4	-	nC
Irrm	Peak Reverse Recovery Current	di/dt =100A/µs	-	2.1	-	А

Notes:

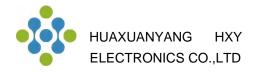
1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, t \leq 10 sec.

3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

4. Guaranteed by design, not subject to production

5. V_DD=50 V, R_G=50 $\Omega,$ L=0.3 mH, starting T_j=25 $^\circ\text{C}$



Si2328DS-T1-GE3 N-SGT Enhancement Mode MOSFET

Typical Characteristics

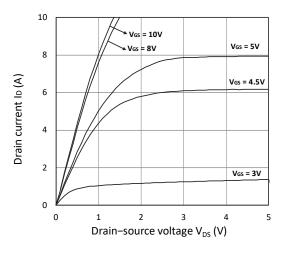


Figure 1. Output Characteristics

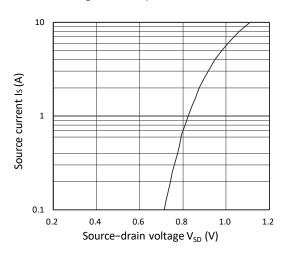


Figure 3. Forward Characteristics of Reverse

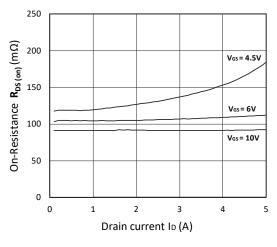


Figure 5. $R_{DS(ON)}$ vs. I_D

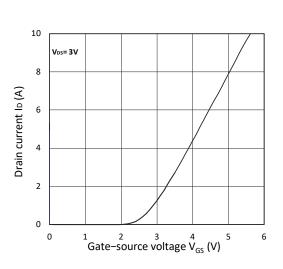


Figure 2. Transfer Characteristics

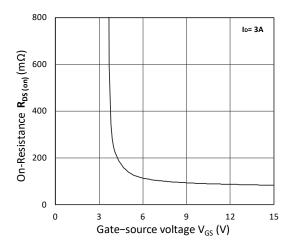


Figure 4. $R_{\text{DS}(\text{ON})}~~\text{vs.}~V_{\text{GS}}$

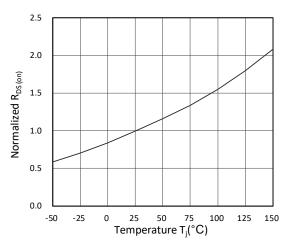


Figure 6. Normalized R_{DS(on)} vs. Temperature



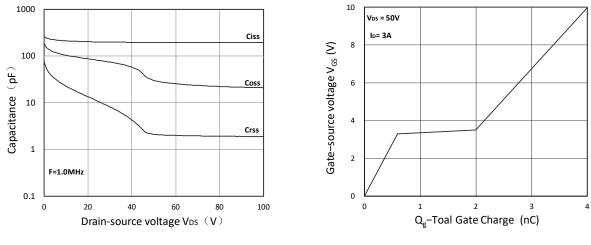
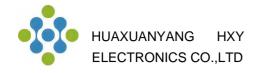
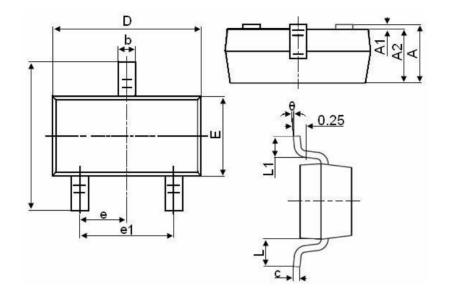


Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics



SOT-23-3L Package Information



Symbol	Dimensions in Millimeters		
	MIN.	MAX.	
A	1.050	1.250	
A1	0.000	0.100	
A2	1.050	1.150	
b	0.300	0.500	
С	0.100	0.200	
D	2.800	3.000	
E	1.500	1.700	
E1	2.650	2.950	
е	0.950TYP		
e1	1.800	2.000	
L	0.550REF		
L1	0.300	0.600	
θ	0°	8°	



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